


## APPLICATION DATA SHEET

Electronic Version v14

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<b>Title of Invention</b>	[MULTI-CHIP PACKAGE AND MANUFACTURING METHOD THEREOF]	
Application Type : regular, utility Attorney Docket Number : 11239-US-PA		
Correspondence address: Customer Number: 31561		
		
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as our attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.